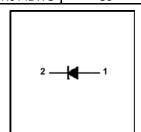


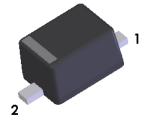
March 2008

1N4148WS / 1N4448WS / 1N914BWS Small Signal Diodes Device Marking Code

- · General Purpose Diodes
- Fast switching Device(TRR < 4.0 ns)
- Very Small and Thin SMD package
- Moisture Level Sensitivity 1
- Pb-free Version and RoHS Compliant
- Matte Tin (Sn) Lead Finish
- Green Mold Compound

Device Marking Code		
Device Type	Device Marking	
1N4148WS	S1	
1N4448WS	S2	
1N914BWS	S3	





*Band Denotes Cathode SOD-323F

Absolute Maximum Ratings* T_a =25°C unless otherwise noted

Symbol	Parameter	Value	Units	
V _{RSM}	Non-Repetitive Peak Reverse Voltage	100	V	
V _{RRM}	Repetitive Peak Reverse Voltage	75	V	
I FRM	Repetitive Peak Forward Current	300	mA	
Io	Continuous Forward Current	150	mA	
TJ	Operating Junction Temperature Range	+150	°C	
T _{STG}	Storage Temperature Range	-55 to +150	°C	

^{*} These ratings are limiting values above which the serviceability of any semiconductor device may be impaired. The factory should be consulted on applications involving pulsed or low duty cycle operations.

Thermal Characteristics

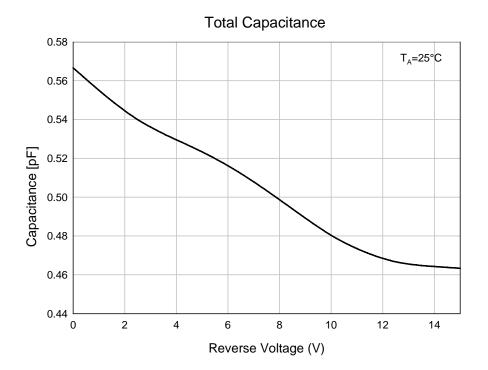
Symbol	Parameter	Value	Unit
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	500	°C/W
P _D	Power Dissipation(T _C =25°C)	200	mW

^{*} Device mounted on FR-4 PCB minimum land pad.

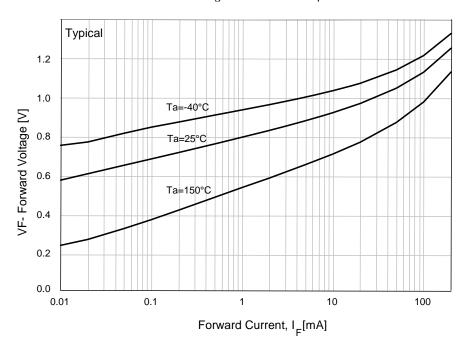
Electrical Characteristics T_a=25°C unless otherwise noted

Symbol	Parameter		Test Conditions	Min	Тур	Max	Units
BV _R	Breakdown Voltage		I _R = 100 μA I _R = 5 μA	100 75			V
I _R	Reverse Current		V _R = 20 V V _R = 75 V			25 5	nA μA
V _F	Forward Voltage	1N4448WS/ 914BWS 1N4148WS 1N4448WS/ 914BWS	$I_F = 5 \text{ mA}$ $I_F = 10 \text{ mA}$ $I_F = 100 \text{ mA}$	0.62		0.72 1 1	V
C _O	Diode Capacitance		V _R = 0, f = 1 MHz			4	pF
T _{RR}	Reverse Recovery Time		$I_F = 10 \text{ mA}, I_R = 60 \text{mA}$ $I_{RR} = 1 \text{ mA}, R_L = 100 \Omega$			4	nS

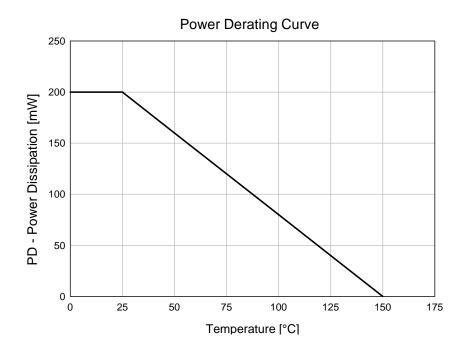
Typical Performance Characteristics

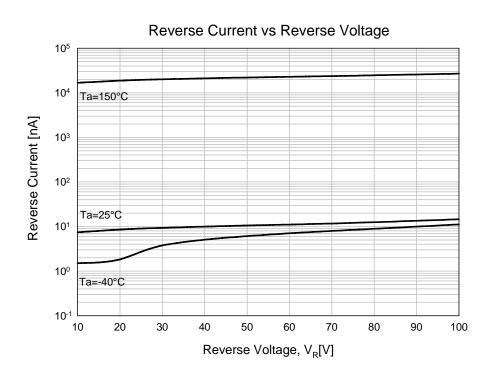


Forward Voltage vs Ambient Temperature

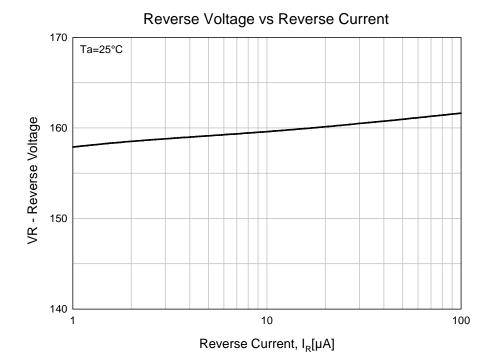


Typical Performance Characteristics



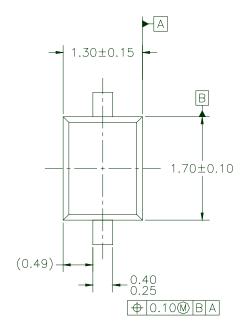


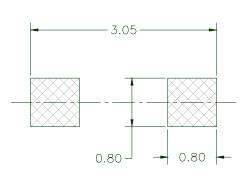
Typical Performance Characteristics



Package Dimensions

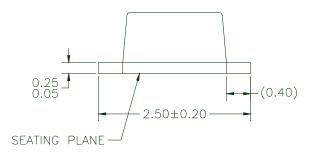
SOD-323F





LAND PATTERN RECOMMENDATION





NOTES: UNLESS OTHERWISE SPECIFIED

- THIS PACKAGE IS COMPLIANT TO JEITA SC90 STANDARD EXCEPT FOR THE OVERALL PACKAGE HEIGHT.
- ALL DIMENSIONS ARE IN MILLIMETERS.
- DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH AND TIE BAR EXTRUSIONS.

DIMENSIONING AND TOLERANCING PER ASME Y14.5M - 1994.

MKT-SOD323F2REV1





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No Identification Needed	Full Production	This datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve design.
Obsolete	Not In Production	This datasheet contains specifications on a product that has been discontinued by Fairchild semiconductor. The datasheet is printed for reference information only.

Rev. I31